

SMQ32SN Series Material Declaration

Total Mass: 28.3 mg



RoHS (2011/65/EC) compliant



Part	Weight of parts (mg)	Content substance		CAS No	Content (mg)	Content (wt%)
Crystal Element	0.3410	Crystal	Silicon dioxide (SiO ₂)	14808-60-7	0.3320	1.17
		Electrode	Chromium (Cr)	7440-47-3	0.0010	0.00
		Electrode	Gold (Au)	7440-57-5	0.0080	0.03
Lead frame	2.1640	42 Alloy	Iron (Fe)	7439-89-6	0.7600	2.69
			Nickel (Ni)	7440-02-0	0.6330	2.24
		Plating	Tin (Sn)	7440-31-5	0.7710	2.73
Case	11.0030	Nickel-Silver	Copper(Cu)	7440-50-8	6.7000	23.71
			Nickel (Ni)	7440-02-0	1.9000	6.72
			Zinc (Zn)	7440-66-6	1.9000	6.72
			Manganese (Mn)	7439-96-5	0.0030	0.01
		Case plating	Nickel (Ni)	7440-02-0	0.5000	1.77
Plug Lead Ring	3.3000	Glass	Silica glass (SiO ₂)	60676-86-0	0.6000	2.12
		Kovar	Iron (Fe)	7439-89-6	0.3000	1.06
			Nickel (Ni)	7440-02-0	0.2000	0.71
			Cobalt (Co)	7440-48-4	0.1000	0.35
		42 Alloy	Iron (Fe)	7439-89-6	0.9000	3.18
			Nickel (Ni)	7440-02-0	0.6000	2.12
		Plating	Copper (Cu)	7440-50-8	0.1000	0.35
			Lead (Pb) *	7439-92-1	0.4500	1.59
			Tin (Sn)	7440-31-5	0.0500	0.18
Resin	11.4530	Epoxy resin	Silica (SiO ₂)	60676-86-0	7.8560	27.80
			Metal hydroxide	-	1.4890	5.27
			Epoxy resin	25068-38-6	1.2600	4.46
			Phenol resin	9003-35-4	0.6870	2.43
			Carbon Black	1333-86-4	0.0460	0.16
			Others	-	0.1150	0.41
Total:	28,26				28,3	100

* Exemptions from RoHS: No 7 (a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)